

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-8. (Canceled)

9. (Previously Presented) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element at a front surface of a substrate;
polishing a back surface of the substrate by a chemical mechanical polishing method to thereby reduce a thickness of the substrate to less than 300 micrometers; and
bonding a color filter at the polished back surface of the substrate.

10. (Currently Amended) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a thin film transistor~~semiconductor element~~ and a light emitting element being electrically connected to the ~~semiconductor element~~thin film transistor at a front surface of a substrate;

polishing a back surface of the substrate by a chemical mechanical polishing method; and
bonding a color filter at the polished back surface of the substrate.

11. (Previously Presented) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a plurality of light emitting elements in a matrix form at a front surface of a first substrate; and

bonding a transparent substrate comprising at least a colored layer at a back surface of the first substrate,

said method further comprising a step of bonding a polarization plate to the transparent substrate.

12. (Previously Presented) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being electrically connected to the semiconductor element at a front surface of a first substrate;

bonding a transparent substrate comprising at least a colored layer at a back surface of the first substrate,

said method further comprising a step of bonding a polarization plate to the transparent substrate.

13. (Canceled)

14. (Original) A method according to claim 11, wherein the transparent substrate comprises a polymeric material.

15-16. (Canceled)

17. (Previously Presented) A method according to claim 11, further comprising the steps of:

polishing the back surface of the first substrate by a chemical mechanical polishing method.

18. (Canceled)

19. (Original) A method according to claim 12, wherein the transparent substrate comprises a polymeric material.

20. (Previously Presented) A method according to claim 12, further comprising the steps of:

polishing the back surface of the first substrate by a chemical mechanical polishing method.

21-22. (Canceled)

23. (Withdrawn): A method of manufacturing a light emitting device comprising:
providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

forming a plurality of color layers over a first surface of a second substrate;

fixing the second substrate to said first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

24. (Withdrawn) The method according to claim 23 wherein said light emitting device is a passive matrix display device.

25. (Withdrawn) The method according to claim 23 wherein said light emitting device is an active matrix display device.

26. (Withdrawn) The method according to claim 23 wherein said electroluminescence layer comprises an organic electroluminescence material.

27. (Withdrawn) A method of manufacturing a light emitting device comprising:
providing a first substrate having a first surface and a second surface opposite to said the first surface;
forming a first electrode over the first surface of the first substrate;
forming an electroluminescence layer over the first electrode; and
forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;
polishing the second surface of the first substrate to thin the first substrate;
forming a plurality of color layers over a first surface of a second substrate;
fixing the second substrate to the thinned first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

28. (Withdrawn) The method according to claim 27 wherein said light emitting device is a passive matrix display device.

29. (Withdrawn) The method according to claim 27 wherein said light emitting device is an active matrix display device.

30. (Withdrawn) The method according to claim 27 wherein said electroluminescence layer comprises an organic electroluminescence material.

31. (Withdrawn) The method according to claim 27 wherein a thickness of said first substrate after the step of polishing is 300 μm or less.

32. (Withdrawn) A method of manufacturing a light emitting device comprising:
providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

providing a second substrate having a first surface and a second surface opposite to said second surface wherein said second substrate comprises a plastic material and each of the first and second surfaces of the second substrate are coated with a protective film;

forming a plurality of color layers over the second substrate;

fixing the second substrate to said first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

33. (Withdrawn) The method according to claim 32 wherein said light emitting device is a passive matrix display device.

34. (Withdrawn) The method according to claim 32 wherein said light emitting device is an active matrix display device.

35. (Withdrawn) The method according to claim 32 wherein said electroluminescence layer comprises an organic electroluminescence material.

36. (Withdrawn) The method according to claim 32 wherein said protective film comprises diamond like carbon.

37. (Withdrawn) A method of manufacturing a light emitting device comprising:
providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode;

polishing the second surface of the first substrate to thin the first substrate;

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

providing a second substrate having a first surface and a second surface opposite to said second surface wherein said second substrate comprises a plastic material and each of the first and second surfaces of the second substrate are coated with a protective film;

forming a plurality of color layers over the second substrate;

fixing the second substrate to the thinned first substrate with said plurality of color layers; interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

38. (Withdrawn) The method according to claim 37 wherein said light emitting device is a passive matrix display device.

39. (Withdrawn) The method according to claim 37 wherein said light emitting device is an active matrix display device.

40. (Withdrawn) The method according to claim 37 wherein said electroluminescence layer comprises an organic electroluminescence material.

41. (Withdrawn) The method according to claim 37 wherein a thickness of said first substrate after the step of polishing is 300 μm or less.

42. (Withdrawn) The method of claim 9 wherein the light emitting element comprises an electroluminescence material.

43. (Withdrawn) The method of claim 10 wherein the light emitting element comprises an electroluminescence material.

44. (Withdrawn) The method of claim 11 wherein the light emitting element comprises an electroluminescence material.

45. (Withdrawn) The method of claim 12 wherein the light emitting element comprises an electroluminescence material.

46. (Currently Amended) The method according to claim 10, wherein a thickness of the substrate is less than 300 [μm] after the polishing step.

47. (Previously Presented) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element at a front surface of a first substrate; and

bonding a transparent substrate comprising at least a colored layer at a back surface of the first substrate,

said method further comprising a step of bonding an antireflection film to the transparent substrate.

48. (Previously Presented) The method according to claim 47, wherein the transparent substrate comprises a polymeric material.

49. (Previously Presented) The method according to claim 47, further comprising the steps of:

polishing the back surface of the first substrate by a chemical mechanical polishing method.

50. (Previously Presented) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being electrically connected to the semiconductor element at a front surface of a first substrate;

bonding a transparent substrate comprising at least a colored layer at a back surface of the first substrate,

said method further comprising a step of bonding an antireflection film to the transparent substrate.

51. (Previously Presented) The method according to claim 50, wherein the transparent substrate comprises a polymeric material.

52. (Previously Presented) The method according to claim 50, further comprising the steps of:

polishing the back surface of the first substrate by a chemical mechanical polishing method.